Serial Number: 10/656,745

Filing Date: September 5, 2003

Title: METHOD AND APPARATUS FOR IMPROVED COATING OF A SEMICONDUCTOR WAFER

IN THE SPECIFICATION

Please amend the specification as follows:

The paragraph beginning at page 1, is amended as follows:

This application is a continuation of U.S. App. Ser. No. 10/155,450, filed May [0001] 22, 2002 and issued as U.S. Pat. No. 6,666,917; which is a divisional of U.S. App. Ser. No.09/292,081, filed Apr. 14, 1999 and issued as U.S. Pat. No. 6,423,380; which is a continuation of U.S. App. Ser. No. 08/949,072, filed Oct. 10, 1997 and issued as U.S. Pat. No. 5,902,399; which is a continuation of U.S. App. Ser. No. 08/508,051, filed Jul. 27, 1995, and now abandoned.